

L Number	Hits	Search Text	DB	Time stamp
-	338712	Cu or copper	USPAT; US-PGPUB	2003/04/30 12:11
-	263262	barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier"	USPAT; US-PGPUB	2003/04/30 12:11
-	457614	nitriding or nitrogen or ammonia	USPAT; US-PGPUB	2003/04/30 12:11
-	20650	(Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)	USPAT; US-PGPUB	2003/04/30 11:51
-	342211	@ad>20010221 or @rlad>20010221	USPAT; US-PGPUB	2003/04/30 11:51
-	16434	((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)	USPAT; US-PGPUB	2003/04/30 11:52
-	566	438/627.ccls.	USPAT; US-PGPUB	2003/04/30 11:52
-	161	(((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/627.ccls.	USPAT; US-PGPUB	2003/04/30 11:52
-	224	removing with "copper oxide"	USPAT; US-PGPUB	2003/04/30 12:15
-	6	((((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/627.ccls.) and (removing with "copper oxide")	USPAT; US-PGPUB	2003/04/30 12:01
-	155	438/630.ccls.	USPAT; US-PGPUB	2003/04/30 12:01
-	24	(((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/630.ccls.	USPAT; US-PGPUB	2003/04/30 12:02
-	2	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/630.ccls.)	USPAT; US-PGPUB	2003/04/30 12:02
-	532	438/631.ccls.	USPAT; US-PGPUB	2003/04/30 12:02
-	43	(((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/631.ccls.	USPAT; US-PGPUB	2003/04/30 12:02
-	1	(removing with "copper oxide") and (((((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/631.ccls.)	USPAT; US-PGPUB	2003/04/30 12:02
-	174	438/635.ccls.	USPAT; US-PGPUB	2003/04/30 12:02
-	20	(((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/635.ccls.	USPAT; US-PGPUB	2003/04/30 12:02
-	2	(removing with "copper oxide") and (((((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/635.ccls.)	USPAT; US-PGPUB	2003/04/30 12:04
-	670	438/643.ccls.	USPAT; US-PGPUB	2003/04/30 12:05

-	182	((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221) and 438/643.ccls.	USPAT; US-PGPUB	2003/04/30 12:05
-	3	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/643.ccls.)	USPAT; US-PGPUB	2003/04/30 12:05
-	171	438/645.ccls.	USPAT; US-PGPUB	2003/04/30 12:05
-	19	((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221) and 438/645.ccls.	USPAT; US-PGPUB	2003/04/30 12:05
-	1	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/645.ccls.)	USPAT; US-PGPUB	2003/04/30 12:05
-	844	438/687.ccls.	USPAT; US-PGPUB	2003/04/30 12:05
-	201	((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221) and 438/687.ccls.	USPAT; US-PGPUB	2003/04/30 12:06
-	11	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/687.ccls.)	USPAT; US-PGPUB	2003/04/30 12:10
-	366	438/906.ccls.	USPAT; US-PGPUB	2003/04/30 12:10
-	32	((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221) and 438/906.ccls.	USPAT; US-PGPUB	2003/04/30 12:10
-	1	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/906.ccls.)	USPAT; US-PGPUB	2003/04/30 12:10
-	24	438/for.111.ccls.	EPO; JPO; DERWENT	2003/04/30 12:10
-	237858	nitriding or nitrogen or ammonia	EPO; JPO; DERWENT	2003/04/30 12:11
-	158052	barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier"	EPO; JPO; DERWENT	2003/04/30 12:11
-	592726	Cu or copper	EPO; JPO; DERWENT	2003/04/30 12:11
-	0	438/for.111.ccls. and ((nitriding or nitrogen or ammonia) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (Cu or copper))	EPO; JPO; DERWENT	2003/04/30 12:11
-	1201	438/for.355.ccls.	EPO; JPO; DERWENT	2003/04/30 12:11
-	0	((nitriding or nitrogen or ammonia) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (Cu or copper)) and 438/for.355.ccls.	EPO; JPO; DERWENT	2003/04/30 12:12
-	393	(nitriding or nitrogen or ammonia) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (Cu or copper)	EPO; JPO; DERWENT	2003/04/30 12:12
-	165	removing with "copper oxide"	EPO; JPO; DERWENT	2003/04/30 12:15

-	2	((nitriding or nitrogen or ammonia) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (Cu or copper)) and (removing with "copper oxide")	EPO; JPO; DERWENT	2003/04/30 12:15
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